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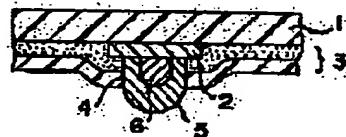
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(54) CIRCUIT BOARD PROVIDED WITH BUMP AND MANUFACTURE THEREOF

(57)Abstract:

PURPOSE: To provide a circuit board provided with a bump having a shape in which the central part of a copper bump is constituted to be a convex shape.
CONSTITUTION: A required circuit wiring pattern 2 is provided at least on one face of an insulating base material 1, an insulating surface protective layer 3 is arranged and formed on the surface of the circuit wiring pattern 2, a hole 4, for continuity use, which reaches the circuit wiring pattern 2 is formed in the insulating surface protective layer 3, and one end of the hole 4 for continuity use is brought into electric continuity with the circuit wiring pattern 2. The other end is provided with a bump 5 which protrudes toward the outside and on which a circuit component is mounted, the bump 5 is provided with a central nucleus 6 in the bottom center of the hole 4 for continuity use, and its central part is formed to be a convex shape.



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